

3/22/02

EQUIVALENT TO 09/914,077

L1 ANSWER 1 OF 1 WPIX COPYRIGHT 2002 DERWENT INFORMATION LTD
AN 2001-111978 [12] WPIX
DNN N2001-082259
TI IC device, e.g. for contactless data carrier, has multilayer structure with metallized layers forming coil around storage chip.
DC P76 T04 U12 U13 U14 W02
IN KAWAMURA, S; SHIMIZU, S
PA (HITM) HITACHI MAXELL KK
CYC 89
PI WO 2000051181 A1 20000831 (200112)* JA 41p H01L025-00
AU 2000026904 A 20000914 (200112) H01L025-00
JP 2000323643 A 20001124 (200112) 14p H01L025-00
ADT WO 2000051181 A1 WO 2000-JP1029 20000223; AU 2000026904 A AU 2000-26904
20000223; JP 2000323643 A JP 2000-44765 20000222
FDT AU 2000026904 A Based on WO 200051181
PRAI JP 1999-59753 19990308; JP 1999-46545 19990224
IC ICM H01L025-00
ICS B42D015-10; G06K019-07; G06K019-077
AB WO 200051181 A UPAB: 20010302
NOVELTY - The IC device includes a conductor constituting a coil (3) and having a multilayer structure comprising a sputtered or vapor deposited metal layer and a metal plating layer which may be formed by precision electrocasting. The information carrier includes an IC device (1) disposed at the planar center of a base. The carrier may be produced by mounting a required part including an IC device on a band-form base and punching the base to produce the required individual units.
DETAILED DESCRIPTION - INDEPENDENT CLAIMS are included for:
(1) an IC device production method;
(2) an information carrier mounted with an IC device;
(3) and a production method for an information carrier mounted with an IC device.
USE - As a contactless data carrier interrogated via e.g. an inductive link.
ADVANTAGE - The IC device has an improved communication range for reading and writing into the information carrier.
Dwg.1A/22
FS EPI GMPI
FA AB; GI
MC EPI: T04-K01; U12-C03; U12-Q; U13-D04; U13-E03; U14-H01C; W02-B01A;
W02-C02B; W02-C02G7; W02-G05A